



Semiconductor Device Type: KDX VQFN-100-12x120.9mm-MatteTin						Package Homogeneous Materials					
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	7.04	(mg) Total	Die	% of Total Weight	1.67	
Silicon	7440-21-3	Die	1.67	7.04	16684		Silicon	7440-21-3	100.00		
Epoxy Resin	Trade secret	Mold Compound	3.99	16.85	39926	Total 100.00					
Phenol Resin	Trade secret	Mold Compound	1.33	5.62	13309						
Silica(Amorphous) A	60676-86-0	Mold Compound	34.91	147.33	349129	395.83	(mg) Total	Mold Compound	% of Total Weight	93.80	
Silica(Amorphous) B	7631-86-9	Mold Compound	3.99	16.85	39926		Epoxy Resin	Trade secret	4.26		
Carbon Black	1333-86-4	Mold Compound	0.13	0.56	1331		Phenol Resin	Trade secret	1.42		
Copper	7440-50-8	Mold Compound	49.44	208.63	494411		Silica(Amorphous) A	60676-86-0	37.22		
Nickel	7440-02-0	Leadframe	1.56	6.57	15580		Silica(Amorphous) B	7631-86-9	4.26		
Silicon	7440-21-3	Leadframe	0.34	1.42	3376		Carbon Black	1333-86-4	0.14		
Magnesium	7439-95-4	Leadframe	0.08	0.33	779		Copper	7440-50-8	52.71		
Silver	7440-22-4	Leadframe	0.52	2.19	5193	Total 100.00					
Silver	7440-22-4	Die Attach Material	0.25	1.05	2499						
Acrylic resin	Trade secret	Die Attach Material	0.03	0.13	304	10.52	(mg) Total	Leadframe	% of Total Weight	2.49	
Polybutadiene derivative	Trade secret	Die Attach Material	0.02	0.07	169		Nickel	7440-02-0	62.50		
Butadiene copolymer	Trade secret	Die Attach Material	0.01	0.02	51		Silicon	7440-21-3	13.54		
Acrylate	Trade secret	Die Attach Material	0.02	0.09	203		Magnesium	7439-95-4	3.12		
Epoxy resin	Trade secret	Die Attach Material	0.01	0.04	84		Silver	7440-22-4	20.83		
Peroxide	Trade secret	Die Attach Material	0.00	0.01	17	Total 100.00					
Additive	Trade secret	Die Attach Material	0.01	0.02	51						
Copper	7440-50-8	Bonding Wire	0.35	1.49	3531	1.42	(mg) Total	Die Attach Material	% of Total Weight	0.34	
Palladium	2023568	Bonding Wire	0.01	0.03	65		Silver	7440-22-4	74.00		
Gold	7440-57-5	Bonding Wire	0.00	0.00	5		Acrylic resin	Trade secret	9.00		
Other	Trade Secret	Bonding Wire	0.00	0.00	2		Polybutadiene derivative	Trade secret	5.00		
Tin	7440-31-5	Lead Finish Plating	1.34	5.64	13376		Butadiene copolymer	Trade secret	1.50		
421.98 mg Total Mass			TOTALS:	100.00	421.98	1,000,000		Acrylate	Trade secret	6.00	
									Epoxy resin	Trade secret	2.50
									Peroxide	Trade secret	0.50
									Additive	Trade secret	1.50
									Total 100.00		
						1.52	(mg) Total	Bonding Wire	% of Total Weight	0.36	
							Copper	7440-50-8	98.00		
							Palladium	2023568	1.80		
							Gold	7440-57-5	0.15		
							Other	Trade Secret	0.05		
						Total 100.00					
						5.64	(mg) Total	Lead Finish Plating	% of Total Weight	1.34	
							Tin	7440-31-5	100.00		
						421.98	Total		100.00	100.00	

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